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## Intel - 5SGXEA5N2F45I3L Datasheet



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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

## Details

Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	840
Number of Gates	·
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FBGA, FC (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea5n2f45i3l

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This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min <sup>(4)</sup>	Тур	Max <sup>(4)</sup>	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V <sub>CC</sub>	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) <sup>(3)</sup>	_	0.82	0.85	0.88	V
V <sub>CCPT</sub>	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V <sub>CCPD</sub> <sup>(1)</sup>	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V <sub>CCIO</sub>	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V <sub>CCPGM</sub>	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V <sub>CCA_FPLL</sub>	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V <sub>CCD_FPLL</sub>	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V <sub>CCBAT</sub> (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V <sub>0</sub>	Output voltage	—	0	—	V <sub>CCIO</sub>	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
			0.82	0.85	0.88	
V <sub>CCR_GXBR</sub>	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Receiver analog power supply (right side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V <sub>CCR_GTBR</sub>	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V <sub>CCT_GXBL</sub> Tr	Transmitter analog newer supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
	Transmitter analog power supply (left side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V <sub>CCT_GXBR</sub>	Transmitter analog nower supply (right side)	GX, GS, GT	0.87	0.90	0.93	v
(2)	Transmitter analog power supply (right side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V <sub>CCT_GTBR</sub>	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCL\_GTBR}$	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Table 7.	Recommended Transceiver Power Supply Operating Conditions for Stratix V GX,	GS, and GT Devices
(Part 2	of 2)	

## Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

			Calibration Accuracy					
Symbol	Description	Conditions	C1	C2,12	C3,I3, I3YY	C4,14	Unit	
50-Ω R <sub>S</sub>	Internal series termination with calibration (50- $\Omega$ setting)	V <sub>CCI0</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%	
34-Ω and 40-Ω R <sub>S</sub>	Internal series termination with calibration (34- $\Omega$ and 40- $\Omega$ setting)	V <sub>CCI0</sub> = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%	
48-Ω, 60-Ω, 80-Ω, and 240-Ω R <sub>S</sub>	Internal series termination with calibration (48- $\Omega$ , 60- $\Omega$ , 80- $\Omega$ , and 240- $\Omega$ setting)	V <sub>CCI0</sub> = 1.2 V	±15	±15	±15	±15	%	
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%	
20- $Ω$ , 30- $Ω$ , 40- $Ω$ ,60- $Ω$ , and 120- $Ω$ R <sub>T</sub>	Internal parallel termination with calibration ( $20 \cdot \Omega$ , $30 \cdot \Omega$ , $40 \cdot \Omega$ , $60 \cdot \Omega$ , and $120 \cdot \Omega$ setting)	V <sub>CCI0</sub> = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%	
60-Ω and 120-Ω $R_T$	Internal parallel termination with calibration (60- $\Omega$ and 120- $\Omega$ setting)	V <sub>CCI0</sub> = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%	
$\begin{array}{l} \textbf{25-}\Omega\\ \textbf{R}_{S\_left\_shift} \end{array}$	Internal left shift series termination with calibration (25- $\Omega$ R <sub>S_left_shift</sub> setting)	V <sub>CCI0</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%	

Table 11. OCT Calibration Accurat	y Specifications for Stratix V Devices <sup>(1)</sup> (	(Part 2 of 2)
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## Note to Table 11:

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance to PVT changes.

			<b>Resistance Tolerance</b>					
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
25-Ω R, 50-Ω R <sub>S</sub>	Internal series termination without calibration (25- $\Omega$ setting)	$V_{CCIO} = 3.0$ and 2.5 V	±30	±30	±40	±40	%	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	$V_{CCI0} = 1.8$ and 1.5 V	±30	±30	±40	±40	%	
25-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCI0</sub> = 1.2 V	±35	±35	±50	±50	%	

- You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
- **\*** For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL <sup>(2)</sup>	)		fPLL	
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 <sup>(3)</sup>	14.1	—	6	12.5	_	6	3.125	_	3
x6 <sup>(3)</sup>	_	14.1	6	_	12.5	6	_	3.125	6
x6 PLL Feedback <sup>(4)</sup>	_	14.1	Side- wide	_	12.5	Side- wide		_	_
xN (PCIe)	_	8.0	8	_	5.0	8	_	_	_
VN (Native DHV ID)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above	3.125	3.125	Up to 13 channels above
xN (Native PHY IP)	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.55	7.55	and below PLL	3.120	0.120	and below PLL

Notes to Table 24:

(1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

(2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

(3) Channel span is within a transceiver bank.

(4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Mada (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode <sup>(2)</sup>	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO 3	C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72	
	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76	
	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76	
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
3	2	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	0	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Notes to Table 25:

(1) The maximum data rate is in Gbps.

(2) The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

(3) The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

## Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)<sup>(1)</sup>

Symbol/	Conditions		Transceive Speed Grade			Fransceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	Ī
	100 Hz			-70			-70	
Transmitter REFCLK	1 kHz		_	-90	_	_	-90	-
Phase Noise (622	10 kHz		_	-100	_	_	-100	dBc/Hz
MHz) <sup>(18)</sup>	100 kHz		—	-110	_	—	-110	
	$\geq$ 1 MHz		—	-120	_	—	-120	-
Transmitter REFCLK Phase Jitter (100 MHz) <sup>(15)</sup>	10 kHz to 1.5 MHz (PCIe)		_	3	_		3	ps (rms)
RREF <sup>(17)</sup>	—		1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk <b>clock</b> frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	MHz
Receiver				•				
Supported I/O Standards	—		1.4-V PCMI	_, 1.5-V PCM	L, 2.5-V PCI	ML, LVPEC	L, and LVDS	3
Data rate (Standard PCS) <sup>(21)</sup>	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) <sup>(21)</sup>	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V <sub>MAX</sub> for a receiver pin <sup>(3)</sup>	GT channels	_	_	1.2	_	_	1.2	V
Absolute V <sub>MIN</sub> for a receiver pin	GT channels	-0.4	_	_	-0.4		_	V
Maximum peak-to-peak	GT channels	_	—	1.6	—	—	1.6	V
differential input voltage V <sub>ID</sub> (diff p-p) before device configuration <sup>(20)</sup>	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage $V_{ID}$ (diff p-p) after device configuration ( <sup>16</sup> ), ( <sup>20</sup> )	V <sub>CCR_GTB</sub> = 1.05 V (V <sub>ICM</sub> = 0.65 V)	—	-	2.2	_	_	2.2	V
oomguration ( ), ( )	GX channels		•	•	(8)			
Minimum differential	GT channels	200	_		200			mV
eye opening at receiver serial input pins <sup>(4)</sup> , <sup>(20)</sup>	GX channels				(8)			

Symbol/	Conditions	5	Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors <sup>(7)</sup>	GT channels		100	_	_	100	_	Ω
	85- $\Omega$ setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels <sup>(19)</sup>	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting		150 ± 30%	_	_	150 ± 30%	_	Ω
V <sub>ICM</sub> (AC coupled)	GT channels		650		—	650	—	mV
	VCCR_GXB = 0.85 V or 0.9 V		600	_	_	600		mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth		700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth		750	_	_	750	_	mV
t <sub>LTR</sub> <sup>(9)</sup>	—	—	—	10	—	—	10	μs
t <sub>LTD</sub> <sup>(10)</sup>		4			4			μs
t <sub>LTD_manual</sub> <sup>(11)</sup>	—	4	—	—	4	—	_	μs
t <sub>LTR_LTD_manual</sub> <sup>(12)</sup>	_	15			15	—		μs
Run Length	GT channels	_	_	72	—	—	72	CID
nun Lengin	GX channels				(8)			
CDR PPM	GT channels			1000	_	—	1000	± PPM
	GX channels				(8)			
Programmable	GT channels	_	_	14	—	—	14	dB
equalization (AC Gain) <sup>(5)</sup>	GX channels				(8)			
Programmable	GT channels	_	—	7.5	—	—	7.5	dB
DC gain <sup>(6)</sup>	GX channels				(8)			
Differential on-chip termination resistors <sup>(7)</sup>	GT channels	_	100	_	_	100	_	Ω
Transmitter	·1							
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600		12,500	600	_	12,500	Mbps

## Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)<sup>(1)</sup>

# **PLL Specifications**

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to  $85^{\circ}$ C) and the industrial junction temperature range (-40° to  $100^{\circ}$ C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f <sub>IN</sub>	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 <sup>(1)</sup>	MHz
f <sub>INPFD</sub>	Input frequency to the PFD	5	—	325	MHz
f <sub>finpfd</sub>	Fractional Input clock frequency to the PFD	50	—	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f <sub>VCO</sub>	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t <sub>einduty</sub>	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 <sup>(2)</sup>	MHz
f <sub>оит</sub>	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f <sub>out_ext</sub>	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 <sup>(2)</sup>	MHz
t <sub>outduty</sub>	Duty cycle for a dedicated external clock output (when set to <b>50%</b> )	45	50	55	%
t <sub>FCOMP</sub>	External feedback clock compensation time	_	—	10	ns
f <sub>dyconfigclk</sub>	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t <sub>LOCK</sub>	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t <sub>olock</sub>	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f <sub>CLBW</sub>	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t <sub>PLL_PSERR</sub>	Accuracy of PLL phase shift			±50	ps
t <sub>areset</sub>	Minimum pulse width on the areset signal	10	_		ns

Symbol	Parameter	Min	Тур	Max	Unit
+ (3) (4)	Input clock cycle-to-cycle jitter ( $f_{REF} \ge 100 \text{ MHz}$ )	_	—	0.15	UI (p-p)
t <sub>INCCJ</sub> <sup>(3),</sup> <sup>(4)</sup>	Input clock cycle-to-cycle jitter (f <sub>REF</sub> < 100 MHz)	-750	_	+750	ps (p-p)
t	Period Jitter for dedicated clock output (f_{OUT} $\geq$ 100 MHz)	_	_	175 <sup>(1)</sup>	ps (p-p)
t <sub>outpj_dc</sub> <sup>(5)</sup>	Period Jitter for dedicated clock output (f <sub>OUT</sub> < 100 MHz)	_		17.5 <sup>(1)</sup>	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ( $f_{0UT} \geq 100 \text{ MHz})$	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>foutpj_dc</sub> <sup>(5)</sup>	Period Jitter for dedicated clock output in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
+	Cycle-to-Cycle Jitter for a dedicated clock output ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	175	ps (p-p)
t <sub>outccj_dc</sub> <sup>(5)</sup>	Cycle-to-Cycle Jitter for a dedicated clock output (f <sub>0UT</sub> < 100 MHz)	_	_	17.5	mUI (p-p)
<b>+</b> <i>(5)</i>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} $\geq$ 100 MHz)	_	_	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
t <sub>FOUTCCJ_DC</sub> <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{OUT} < 100 \text{ MHz}$ )+	_	_	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
t <sub>outpj_io</sub> (5),	$\begin{tabular}{ c c c c } \hline Period Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} \geq 100 \mbox{ MHz}) \end{tabular} \end{tabular} \end{tabular} \end{tabular} \end{tabular} \end{tabular} \end{tabular}$	600	ps (p-p)		
(8)	Period Jitter for a clock output on a regular I/O (f <sub>OUT</sub> < 100 MHz)	_	_	60	mUI (p-p)
t <sub>FOUTPJ_IO</sub> (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} \ge 100 \text{ MHz}$ )	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL (f <sub>OUT</sub> < 100 MHz)	_	_	60 <sup>(10)</sup>	mUI (p-p)
t <sub>outccj_io</sub> (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} $\geq$ 100 MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{OUT}$ < 100 MHz)	_	_	60 <sup>(10)</sup>	mUI (p-p)
t <sub>foutccj_10</sub> <sup>(5),</sup>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{0UT} \geq 100 \mbox{ MHz})$	_	_	600 <sup>(10)</sup>	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{OUT} < 100 \text{ MHz}$ )	_	_	60	mUI (p-p)
t <sub>casc_outpj_dc</sub>	Period Jitter for a dedicated clock output in cascaded PLLs (f_{0UT} $\geq$ 100 MHz)		_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f <sub>OUT</sub> < 100 MHz)		_	17.5	mUI (p-p)
f <sub>DRIFT</sub>	Frequency drift after PFDENA is disabled for a duration of 100 $\mu s$	_	_	±10	%
dK <sub>BIT</sub>	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k <sub>value</sub>	Numerator of Fraction	128	8388608	2147483648	

Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

## Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter		Тур	Max	Unit
f <sub>RES</sub>	Resolution of VCO frequency ( $f_{INPFD} = 100 \text{ MHz}$ )	390625	5.96	0.023	Hz

#### Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O  $f_{MAX}$  or  $f_{OUT}$  of the PLL.

- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4)  $f_{REF}$  is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10<sup>-12</sup> (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition: a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f<sub>VCO</sub> specification.
- (10) This specification only covers fractional PLL for low bandwidth. The  $f_{VCO}$  for fractional value range 0.05 0.95 must be  $\geq$  1000 MHz, while  $f_{VCO}$  for fractional value range 0.20 0.80 must be  $\geq$  1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The  $f_{VC0}$  for fractional value range 0.05-0.95 must be  $\geq$  1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The  $f_{VC0}$  for fractional value range 0.20-0.80 must be  $\geq$  1200 MHz.

## **DSP Block Specifications**

Table 32 lists the Stratix V DSP block performance specifications.

			I	Peforman	ce						
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit			
Modes using one DSP											
Three 9 x 9	600	600	600	480	480	420	420	MHz			
One 18 x 18	600	600	600	480	480	420	400	MHz			
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz			
One 27 x 27	500	500	500	400	400	350	350	MHz			
One 36 x 18	500	500	500	400	400	350	350	MHz			
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz			
One sum of square	500	500	500	400	400	350	350	MHz			
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz			
		Modes u	sing two l	DSPs	1		•	1			
Three 18 x 18	500	500	500	400	400	350	350	MHz			
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz			
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz			
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz			
One complex 18 x 18	500	500	500	400	400	350	350	MHz			
One 36 x 36	475	475	475	380	380	300	300	MHz			

## Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

# **Periphery Performance**

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

## **High-Speed I/O Specification**

Table 36 lists high-speed I/O timing for Stratix V devices.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 1 of 4)

Sumbol	Conditions	C1			C2, C2L, I2, I2L		C3,	13, 13L	., <b>I</b> 3YY	C4,14			Unit	
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
f <sub>HSCLK_in</sub> (input clock frequency) True Differential I/O Standards	Clock boost factor W = 1 to 40 $^{(4)}$	5		800	5		800	5		625	5		525	MHz
f <sub>HSCLK_in</sub> (input clock frequency) Single Ended I/O Standards <sup>(3)</sup>	Clock boost factor W = 1 to 40 $^{(4)}$	5		800	5	_	800	5		625	5		525	MHz
f <sub>HSCLK_in</sub> (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 $^{(4)}$	5		520	5	_	520	5		420	5		420	MHz
f <sub>HSCLK_OUT</sub> (output clock frequency)	_	5	_	800	5	_	800	5	_	625 (5)	5	_	525 (5)	MHz

i ani o o o i i i i gii	-Speed I/U Specifica		C1				2, I2L		-	., I3YY		C4,I	A	
Symbol	Conditions				-	-	-		-	-		-		Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t <sub>duty</sub>	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t <sub>rise</sub> & t <sub>fall</sub>	Emulated Differential I/O Standards with three external output resistor networks			250			250			250			300	ps
	True Differential I/O Standards	_	_	150	_	_	150	_	_	150	_	_	150	ps
TCCS	Emulated Differential I/O Standards	_		300	_	_	300	_	_	300	_	_	300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150		1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS RX with DPA (12), (14), (15), (16)	150		1600	150		1600	150		1600	150		1250	Mbps
- f <sub>HSDRDPA</sub> (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps

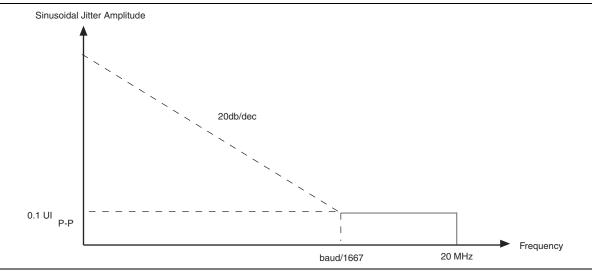
## Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

Jitter Fre	Jitter Frequency (Hz)					
F1	10,000	25.000				
F2	17,565	25.000				
F3	1,493,000	0.350				
F4	50,000,000	0.350				

Table 38.	LVDS Soft-CDR/D	PA Sinusoidal	<b>Jitter Mask Valu</b>	es for a Data Ra	te > 1.25 Gbps
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Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.





## **DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications**

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

#### Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

## Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)

#### Notes to Table 40:

(1) The typical value equals the average of the minimum and maximum values.

(2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t<sub>DQS\_PSERR</sub>) for Stratix V Devices <sup>(1)</sup>

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,14	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

(1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a -2 speed grade is  $\pm 78$  ps or  $\pm 39$  ps.

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Clock Network	Parameter S	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,14		Unit
NELWUIK		-	Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t <sub>JIT(per)</sub>	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	$t_{\rm JIT(cc)}$	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t <sub>JIT(per)</sub>	-75	75	-75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-75	75	-75	75	-90	90	-90	90	ps

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) <sup>(4), (5)</sup>
Stratix V E (1)	5SEE9	—	342,742,976	700,888
	5SEEB	_	342,742,976	700,888

## Table 47. Uncompressed .rbf Sizes for Stratix V Devices

## Notes to Table 47:

(1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.

(2) 36-transceiver devices.

(3) 24-transceiver devices.

(4) File size for the periphery image.

(5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

• For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help.* 

Table 48 lists the minimum configuration time estimates for Stratix V devices.

	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel <sup>(2)</sup>			
Variant		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	A3	4	100	0.534	32	100	0.067	
	AS	4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
GX	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	B9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
ст	C5	4	100	0.675	32	100	0.084	
GT	C7	4	100	0.675	32	100	0.084	

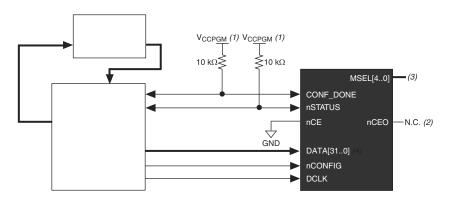
Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FFF X02	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

## Figure 11. Single Device FPP Configuration Using an External Host



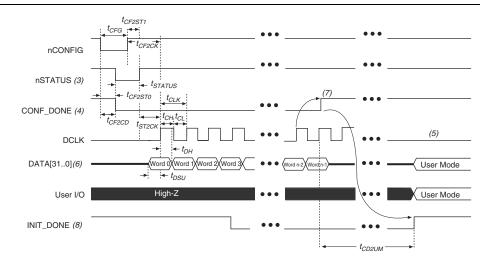
#### Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device.  $V_{CCPGM}$  must be high enough to meet the  $V_{IH}$  specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with  $V_{CCPGM}$ .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

## FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.





#### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nstatus low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT DONE goes low.

# **Active Serial Configuration Timing**

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52.	DCLK Frequency	Specification in the <i>l</i>	AS Configuration Scheme	(1), (2)
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Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

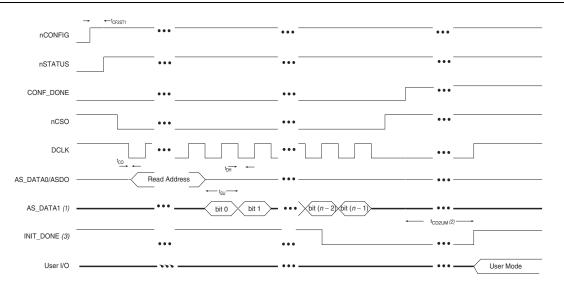
#### Notes to Table 52:

(1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

(2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.





## Notes to Figure 14:

- (1) If you are using AS  $\times 4$  mode, this signal represents the AS\_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 53 lists the timing parameters for AS  $\times 1$  and AS  $\times 4$  configurations in Stratix V devices.

Symbol	Parameter	Minimum	Maximum	Units
t <sub>CO</sub>	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
t <sub>SU</sub>	Data setup time before falling edge on DCLK	1.5	—	ns
t <sub>H</sub>	Data hold time after falling edge on DCLK	0	—	ns

Letter	Subject	Definitions
	V <sub>CM(DC)</sub>	DC common mode input voltage.
	V <sub>ICM</sub>	Input common mode voltage—The common mode of the differential signal at the receiver.
	V <sub>ID</sub>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V <sub>DIF(AC)</sub>	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V <sub>DIF(DC)</sub>	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V <sub>IH</sub>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V <sub>IH(AC)</sub>	High-level AC input voltage
	V <sub>IH(DC)</sub>	High-level DC input voltage
V	V <sub>IL</sub>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V <sub>IL(AC)</sub>	Low-level AC input voltage
	V <sub>IL(DC)</sub>	Low-level DC input voltage
	V <sub>OCM</sub>	Output common mode voltage—The common mode of the differential signal at the transmitter.
	V <sub>OD</sub>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V <sub>SWING</sub>	Differential input voltage
	V <sub>X</sub>	Input differential cross point voltage
	V <sub>OX</sub>	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
X		
Y	_	_
Ζ		

## Table 60. Glossary (Part 4 of 4)